

**DRAPER**

# **Low temperature processing for high temperature conductors: transformational inks**

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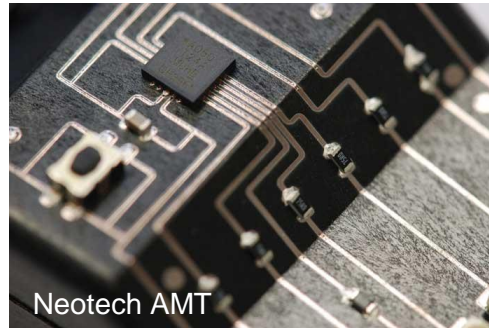
# Outline

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- Current printed conductor: silver
- Transformational printed conductor: High temperature conductor from low temperature inks
- Transformational Materials
  - *Multicomponent particles*
  - *Simultaneous phase transformation and interparticle sintering during flash anneal*
- For Printed Electronics
  - *Printability & ink formulations*
  - *Low temperature substrates during flash anneal*
  - *Electrical performance*

# The Promise of 3D Printed Electronics

- 3D Printing of electronics will change the way we build, repair, integrate, and recycle electronics.



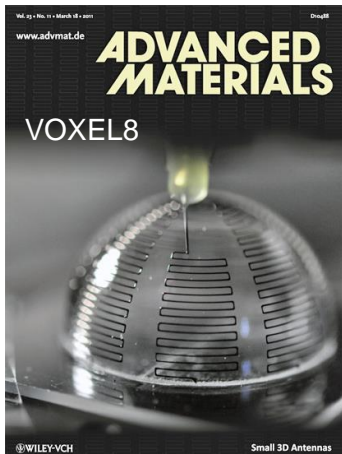
Neotech AMT

Custom 3D Interconnects

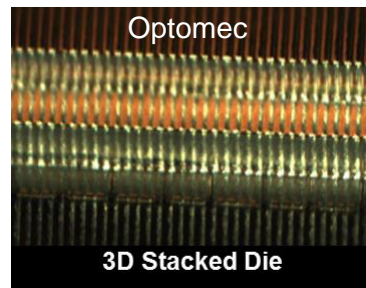


Princeton

Human-Machine Interfaces, Personalized Medicine



Conformal Electronics



Optomec

3D Stacked Die

High Density Die Integration

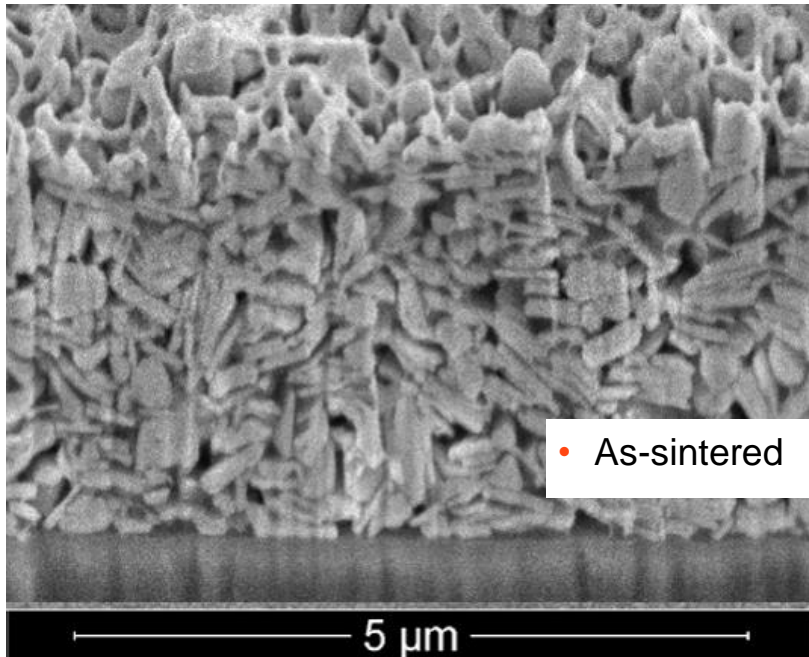


Market for 3D Print Materials to double every 3-4 years with per 2016 Wolhers Report  
 Conductive Materials fastest growing segment per IDtechEx 2016-2026 Forecast

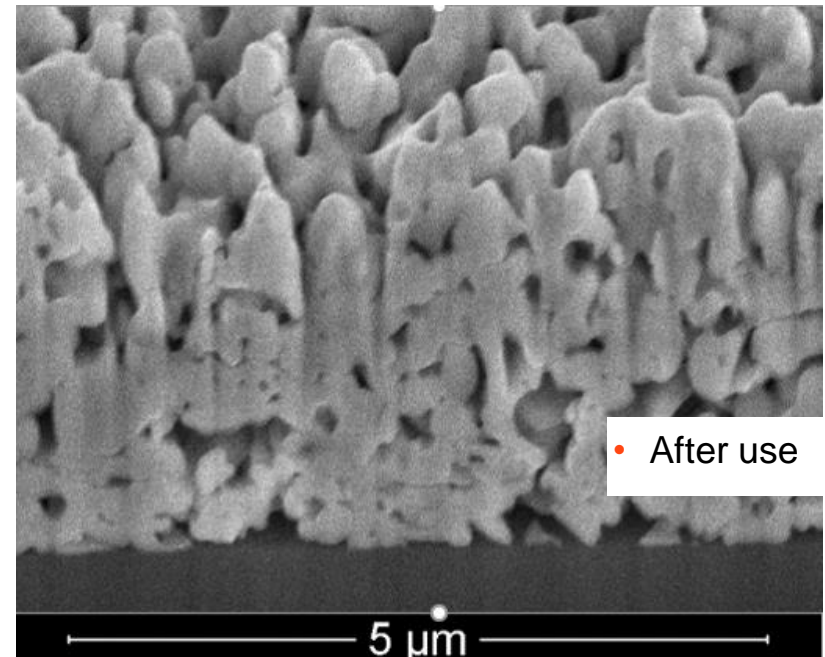
# Workhorse: printed silver

- Nanoparticle silver ink – first commercialized because it can be sintered at low temperatures to high conductivity.
  - *High surface diffusivity aids in sintering*
  - *Still dynamic at operational currents, times, temperatures.*

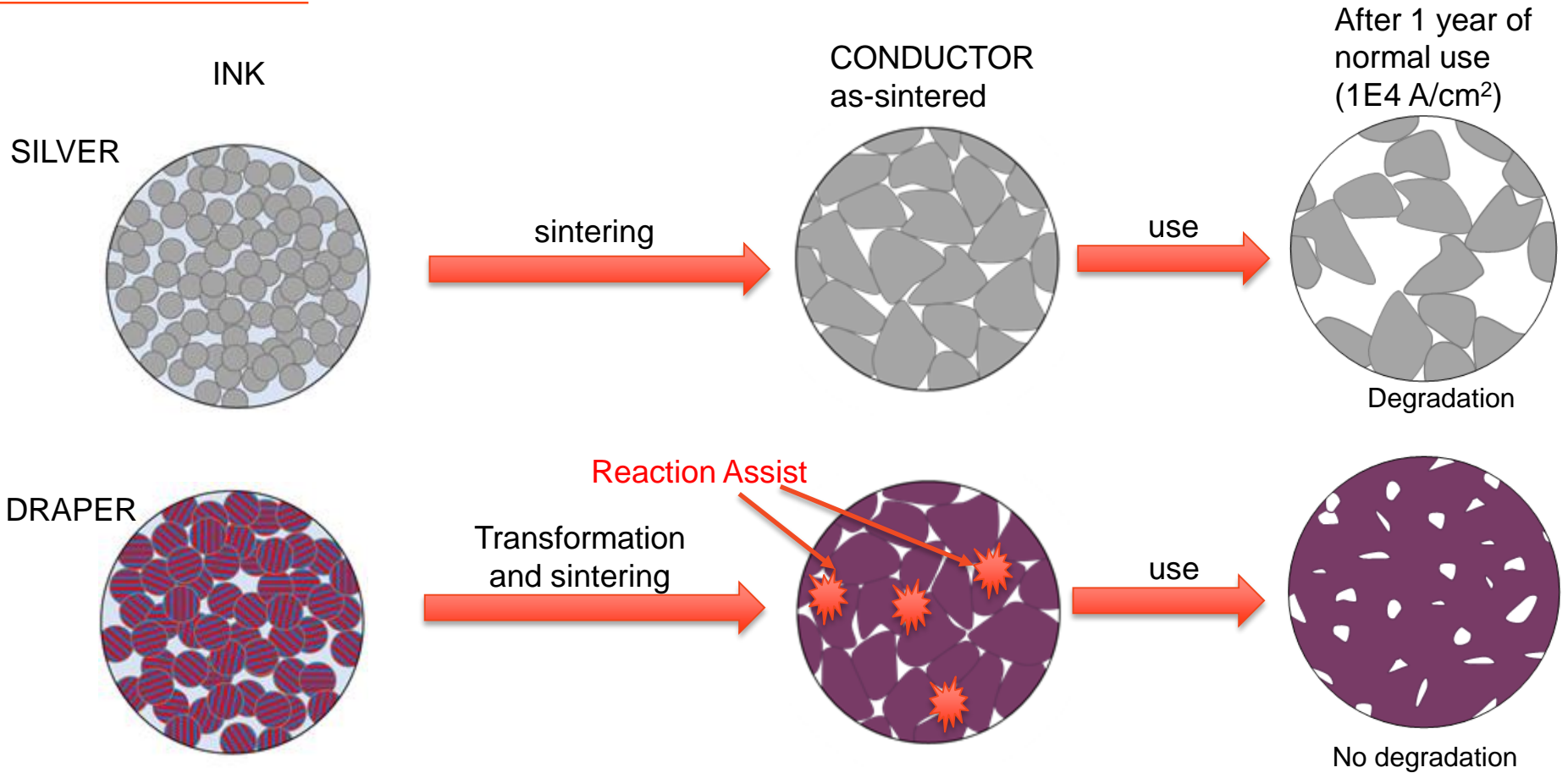
Nanoparticle Ag ink annealed at 200°C for 1 hour



Nanoparticle Ag ink after  $\sim 0.4 \text{ MA/cm}^2$  for 6 weeks



# Exothermic Transformation to High T phase

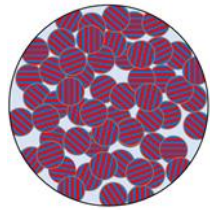


**Metastable INK transforms to a stable CONDUCTOR during sintering.**

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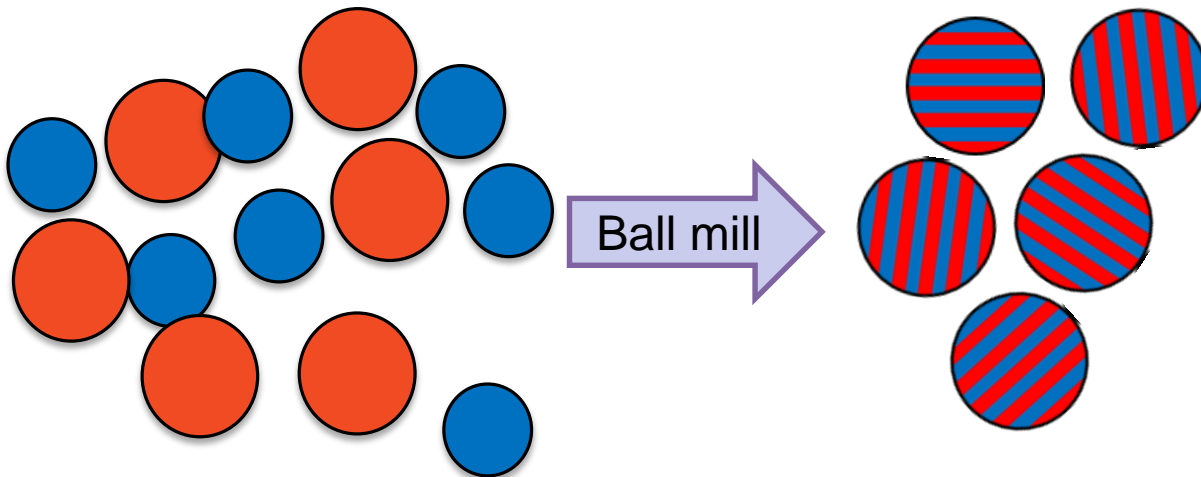
# **Transformation to High Temperature Conductor**

# How to make multi-component particles



## Ball milled particles

- Competition between fragmenting and cold welding



Elemental particles

Composite particles ready to be "inked"

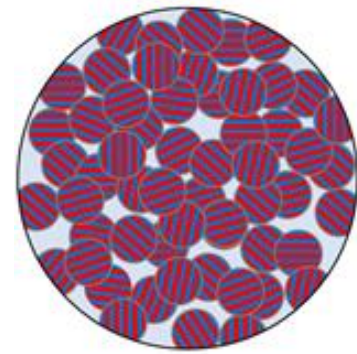
Balls and powder in vial

Batch size = 60 g

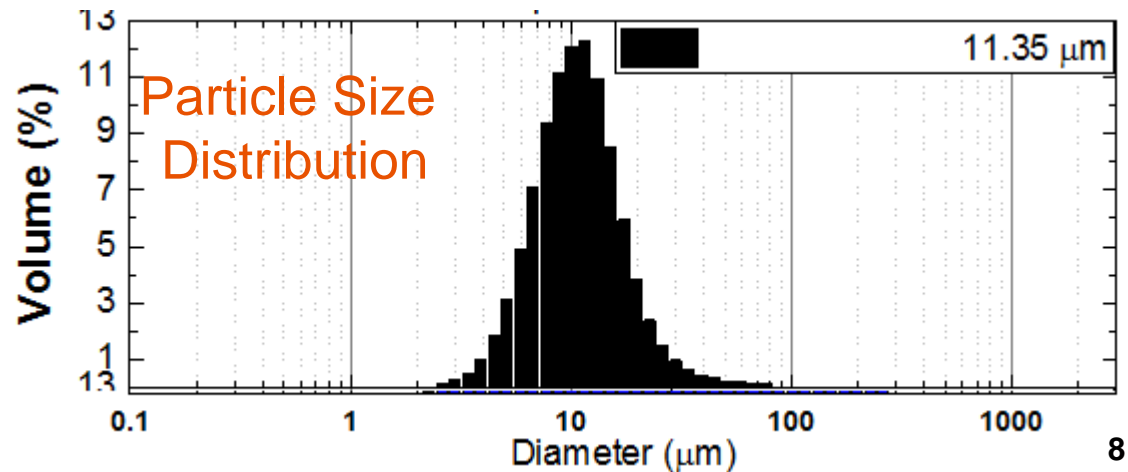
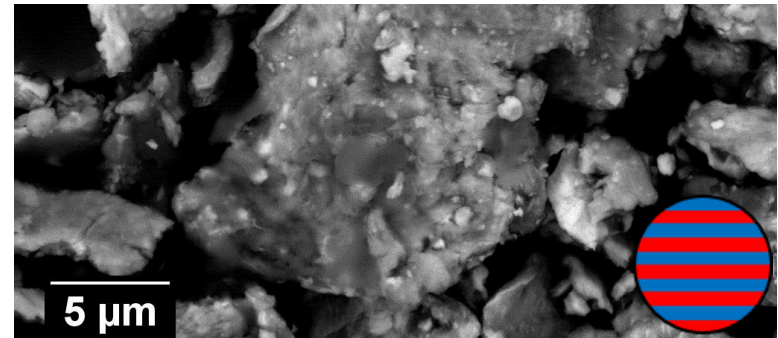
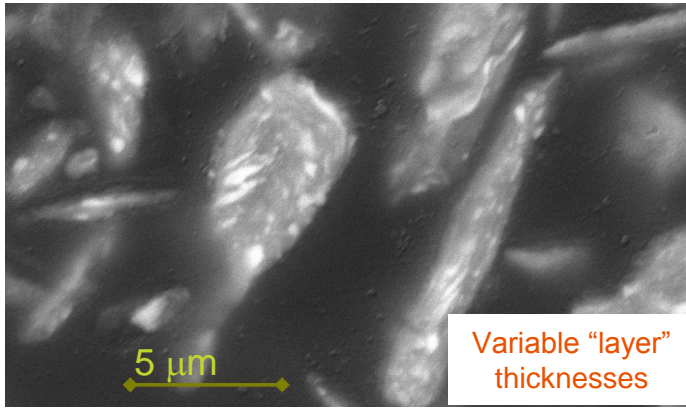


[www.retsch.com](http://www.retsch.com)

# Our multi-component particles



Layers of Constituents that will later transform into Conductor





# Transformation to High Temperature Conductor: Sintering in Pulsed Lamp

- Intense Pulsed Light (IPL) – Xenon lamp
- NovaCentrix PulseForge 1200
  - Also used to sinter nanoparticle silver ink
- Conditions
  - Short Exposure to Lamp Light ~ 1-100 ms



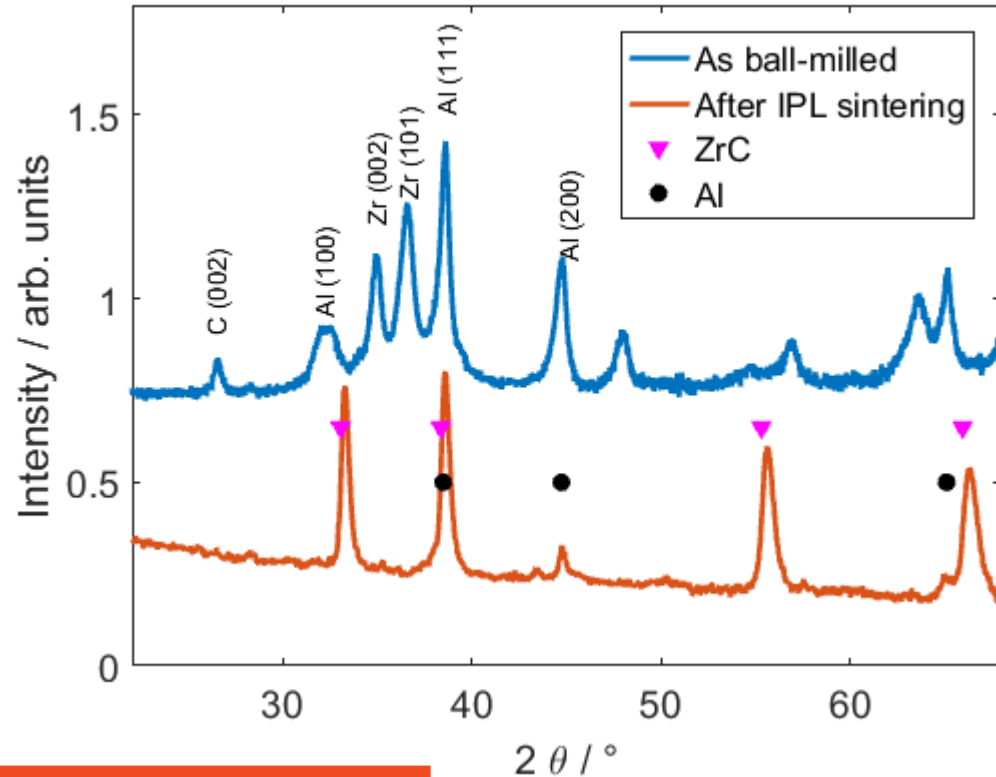
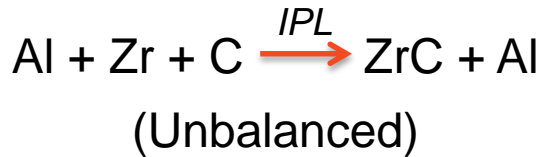
# Transformational Materials



The Al, Zr, C composition is a representative example

Other formulations are developed as well

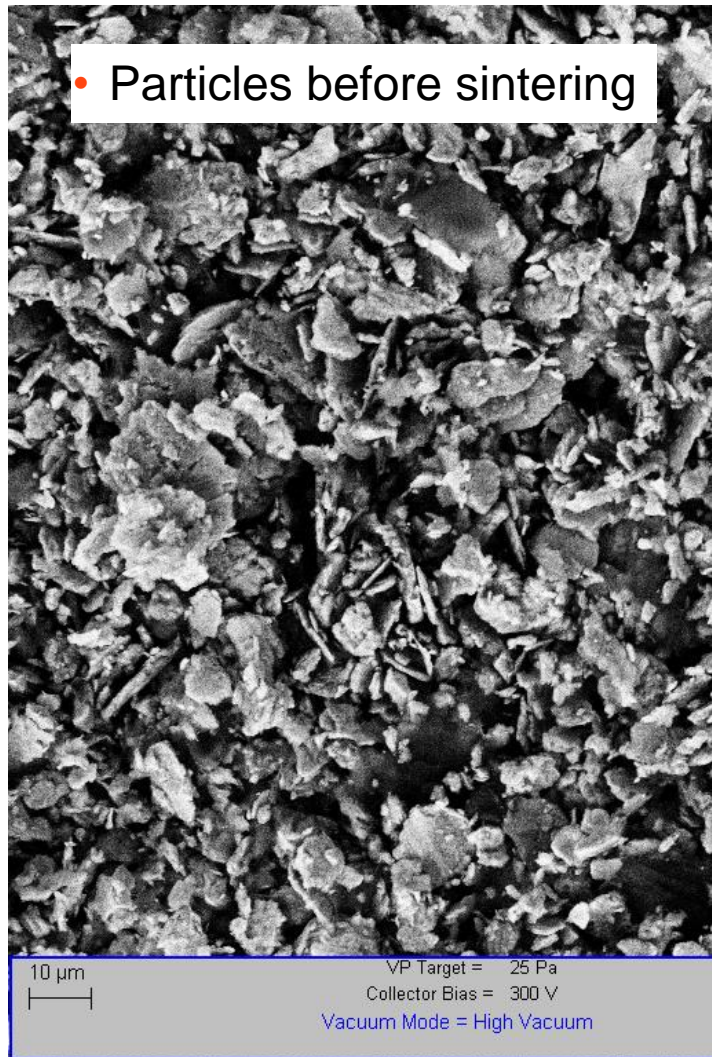
- ***During IPL, a phase transformation occurs.***



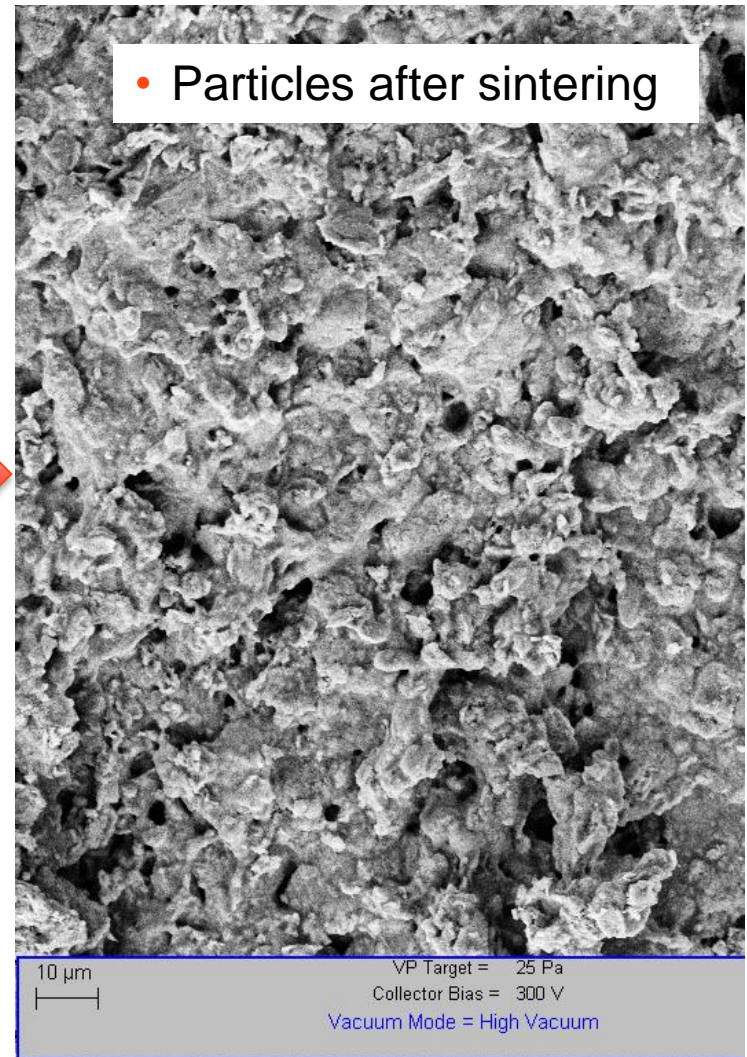
	Crystalline phases (XRD)
Ink particles as printed	Al, Zr, C
Conductor as sintered	ZrC, Al

# Particle sintering during transformation

- Sintering = particles coalescing into a solid form during heat treatment

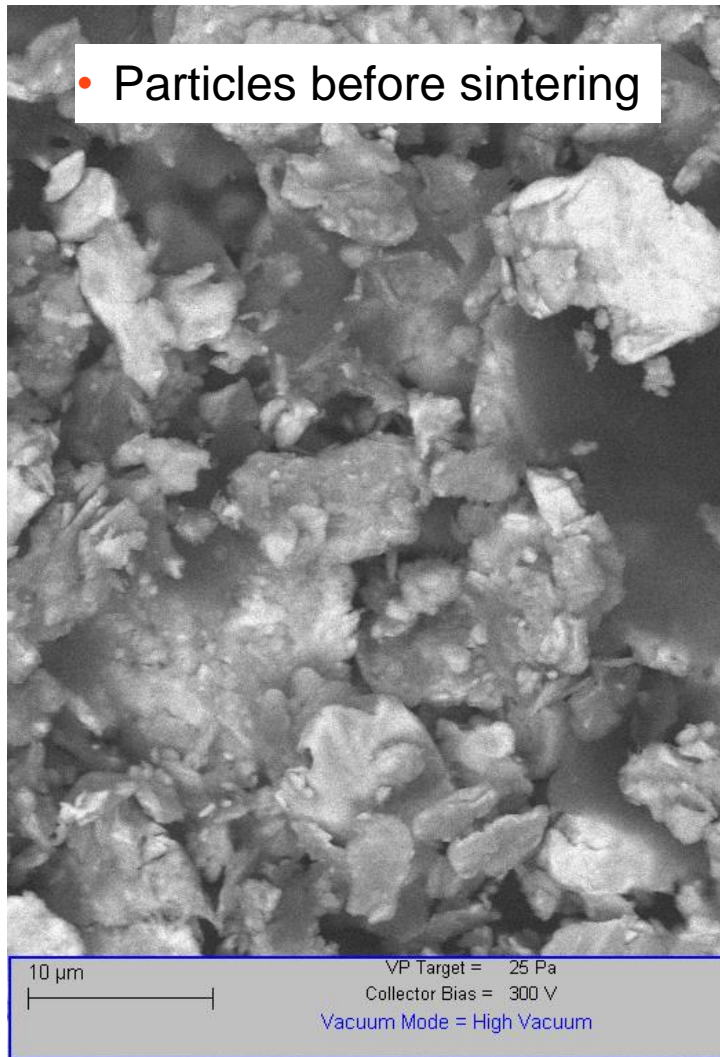


IPL

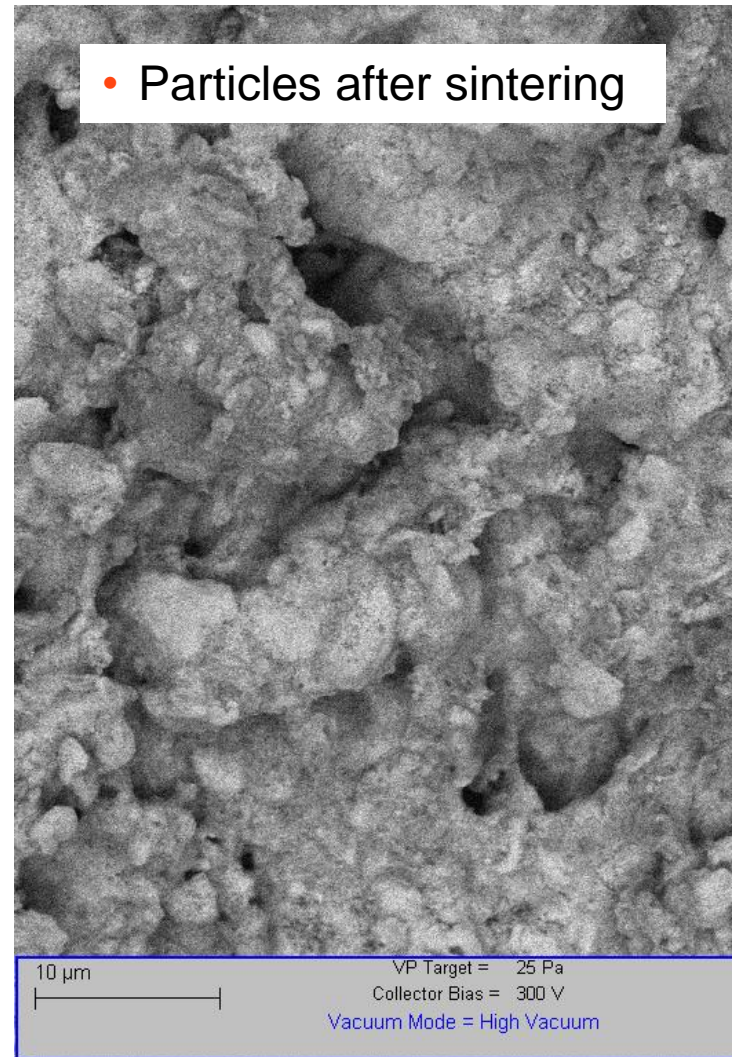


# Particle sintering during transformation

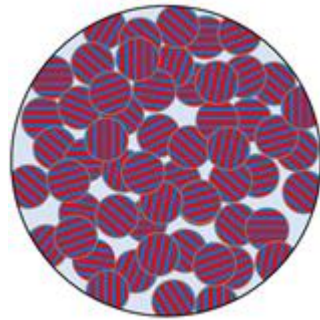
- Sintering = particles coalescing into a solid form during heat treatment



IPL



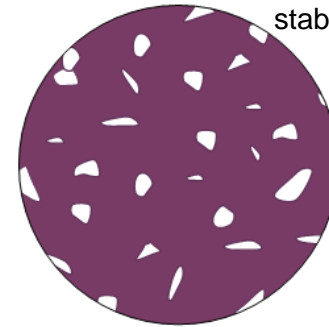
# Transformational Material



Transformation and Sintering

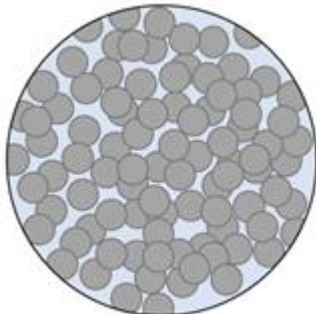


“reaction-assisted sintering”

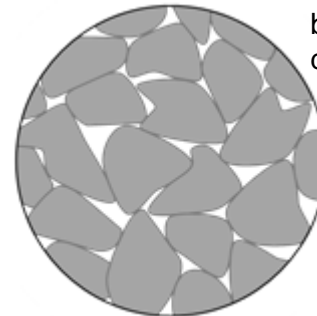


Continuous, porous matrix.  
Now a high temperature-stable phase.

Compare to silver inks:



Sintering only



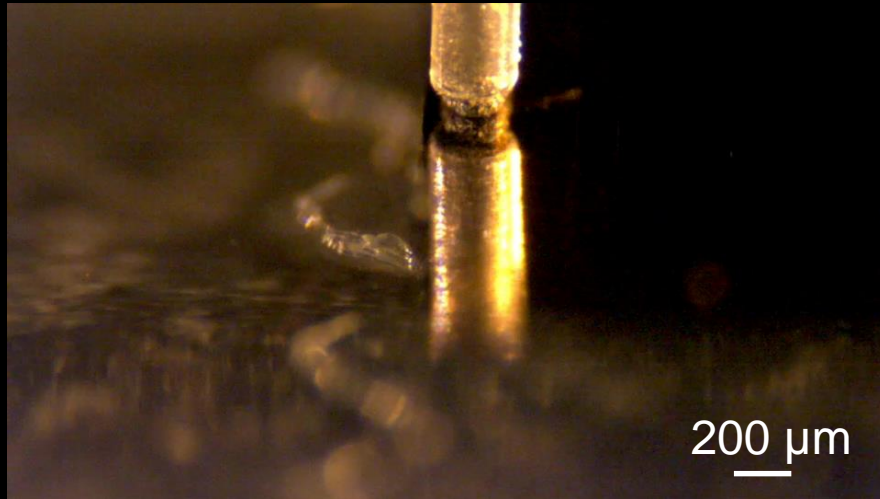
Continuous, porous matrix,  
but still silver & hence  
dynamic under use

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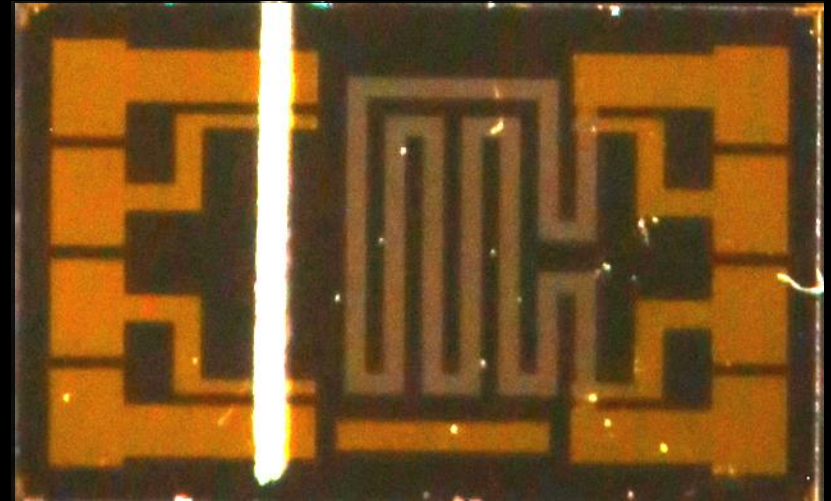
# **Printing and Performance**

# Printing RAIL 3D shear thinning ink

4 Probe Array (real time)



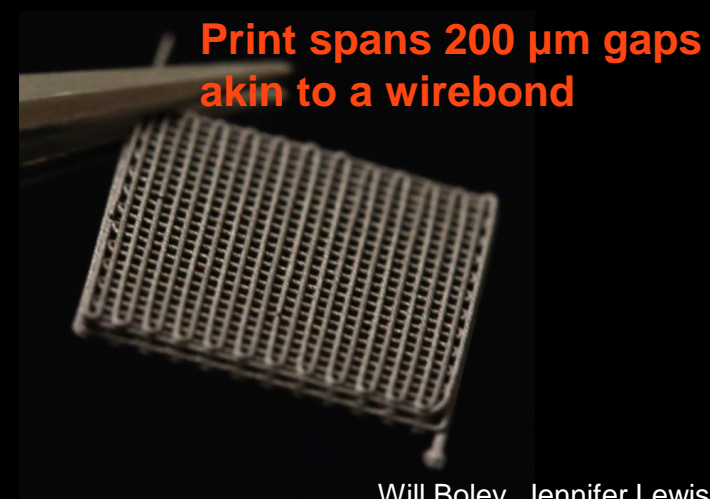
~200 μm Trace on a Probe Device



5 Layer Square Lattice (sped up 8x)



Free standing 1 cm X 1 cm 5 layer lattice



# Printability in different tools

- We have printed our inks with a range of COTS printers without modification

- ***Optomec aerosol-jet printer***

- Can write ink from a stand off distance (up to cm)
- Difficult to write at tight pitch due to overspray

- ***HyRel syringe printer***

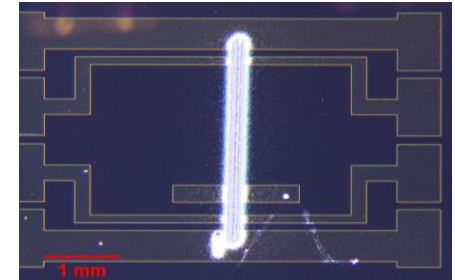
- Uniform deposition of low viscosity inks
- Limited by size (0.5 mm)

- ***Screen Printers***

- Simple, well-known technique
- Limited by size (0.5 mm) and must be on planar surface (can later be flexed)

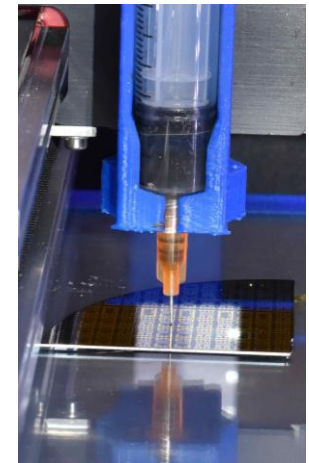
- ***Voxel8 shear thinning type printer***

- Can write tight pitch (~10  $\mu\text{m}$ )
- Must be in contact with print surface & must be high viscosity ink



300  $\mu\text{m}$  wide, 5  $\mu\text{m}$  thick

Draper Ink printed by  
Optomec



Draper Ink in HyRel syringe  
printer

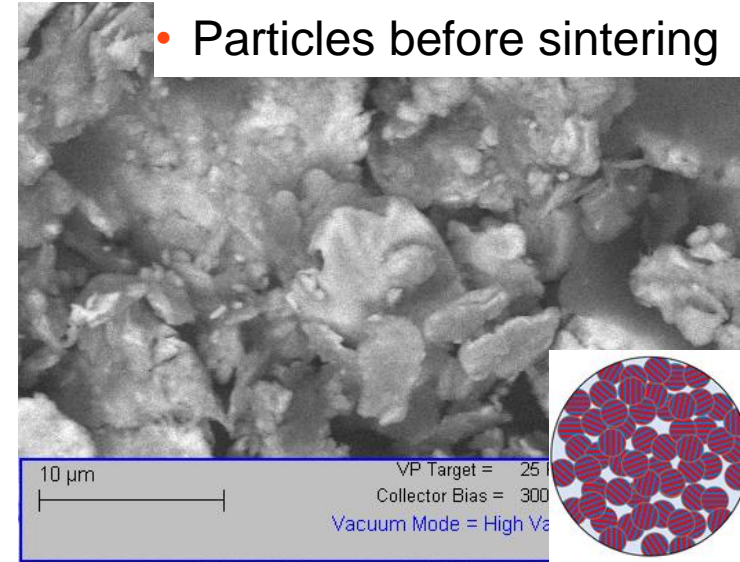


# Transformation to High Temperature Conductor: Sintering in Pulsed Lamp

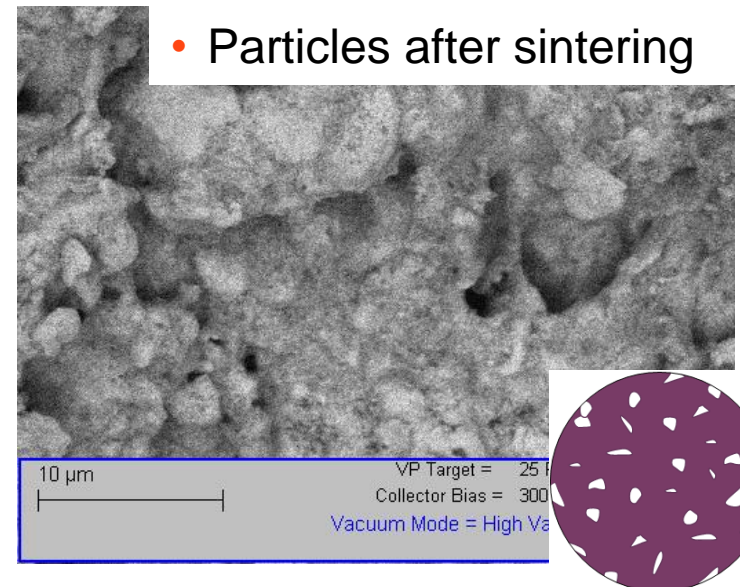
- Intense Pulsed Light (IPL) – Xenon lamp
- NovaCentrix PulseForge 1200
  - Also used to sinter nanoparticle silver ink



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IPL sintering



# Temperature of substrate during IPL

- Substrates stay cool during IPL sintering because they have low absorption of xenon spectrum.

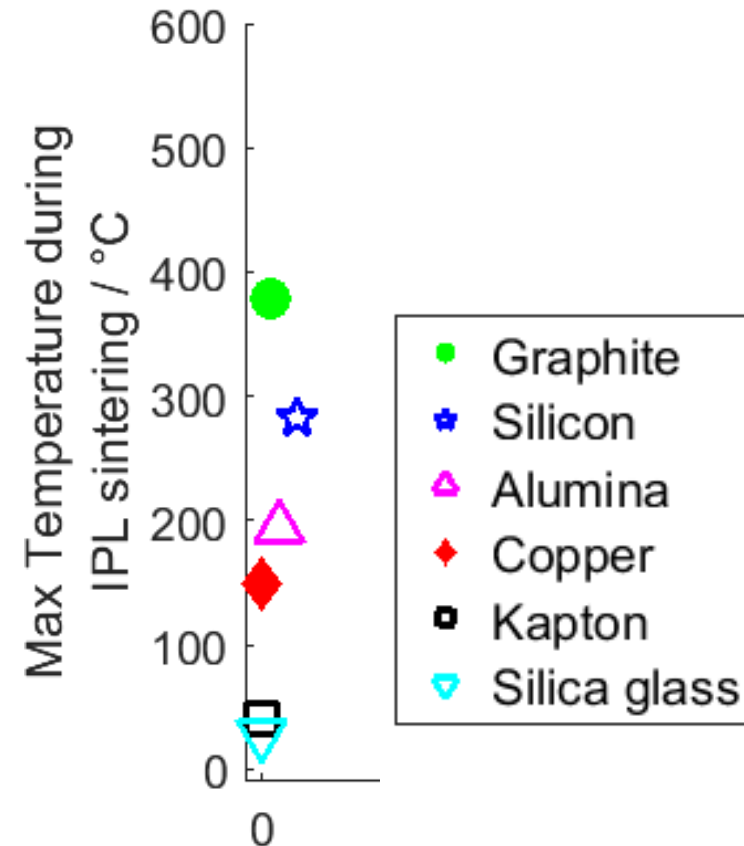
Max temperature of substrate during IPL anneal

- Short Exposure Time
- Substrate cools to  $< 100^{\circ}\text{C}$  in  $< 6$  s

Compare to:

Oven anneals at  $200^{\circ}\text{C}$  for hours

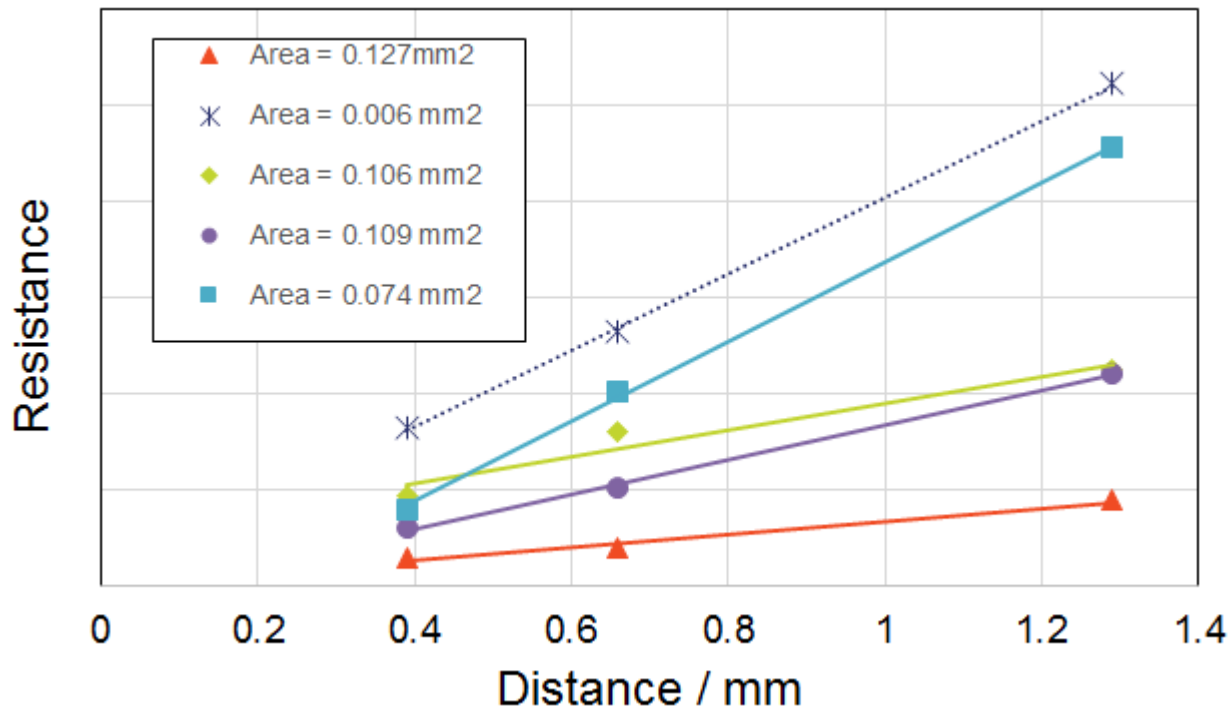
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We've printed on Kapton, glass, FR4, silicon.

# Performance – Resistance per length

- Our printed lines have Resistance per Length  $< 10 \text{ m}\Omega/\text{mm}$ 
  - Cross-sectional areas =  $0.006$  to  $0.130 \text{ mm}^2$



Line with  $1 \text{ mm}^2$  cross-sectional area

Aspect ratios of up to 1:1 can be printed in single pass & sintered in single IPL event

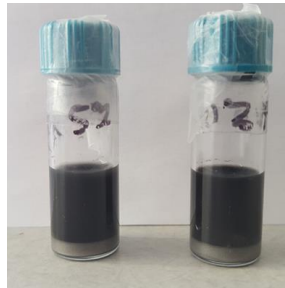
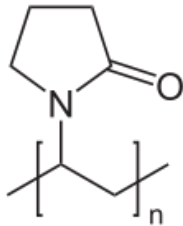
# Designing the ink formulation

*Different printers require different ink formulations*

## Surfactants (1-10 wt. %)

- Functionalize particles' surface to prevent clogging and promote adhesion to substrate

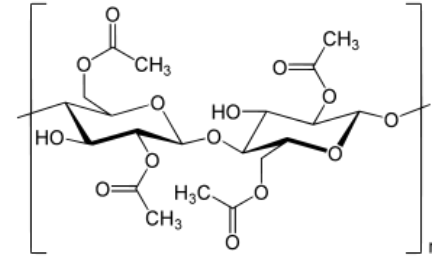
*Example: Polyvinylpyrrolidone (PVP)*



## Thickening Agents (~0-20 wt. %)

- 3D printing (spanning gaps)
- Printing small (~10  $\mu\text{m}$ ) features

*Example: Cellulose Acetate*



## Solvents (~10-40 wt. %)

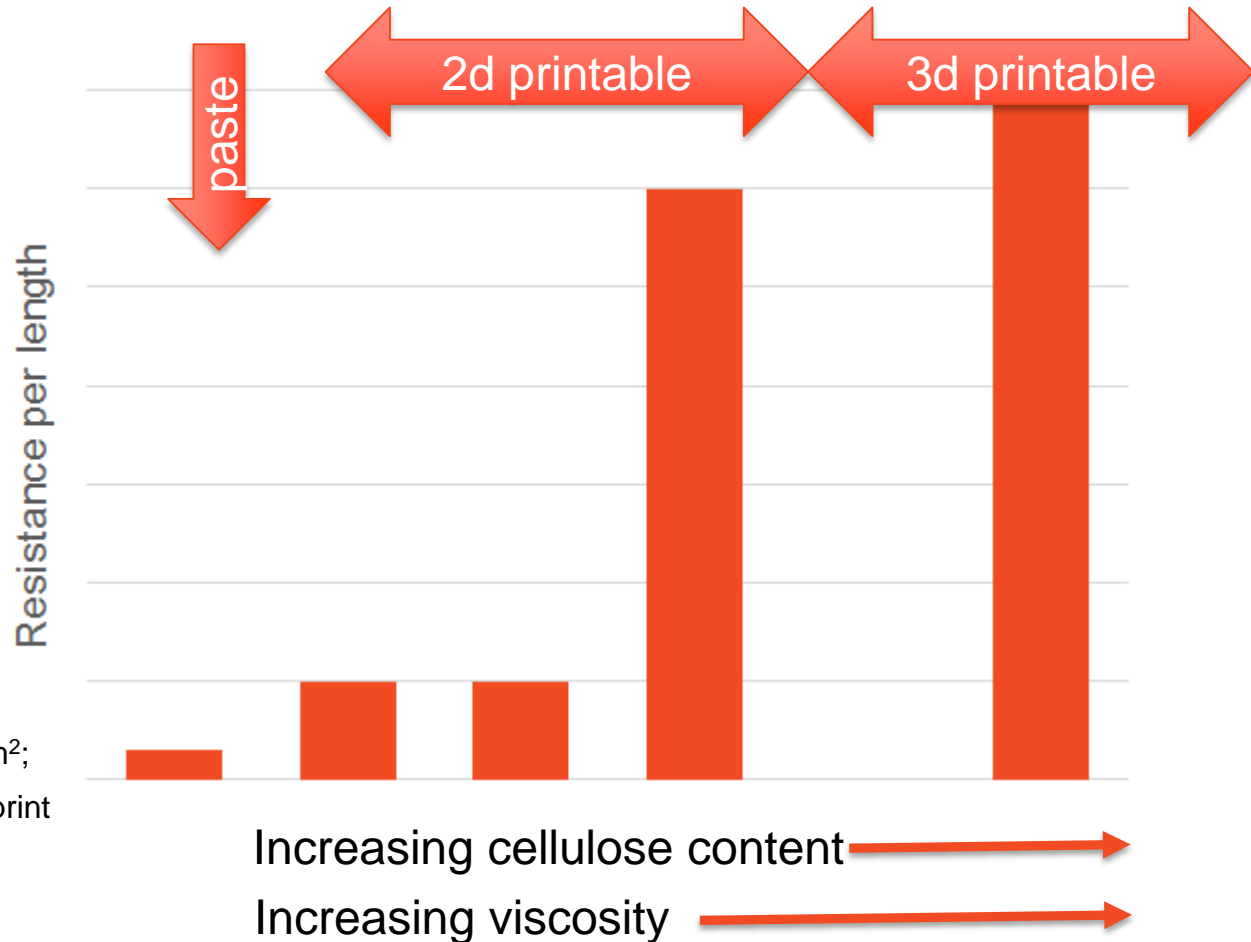
- Suspend the metal particles during printing. Evaporates during curing.

*Example: Isopropanol, DMF, hexane, ethanol*

How do these additives interact with transformational materials?

# Trade-off: Printability vs Low Resistance

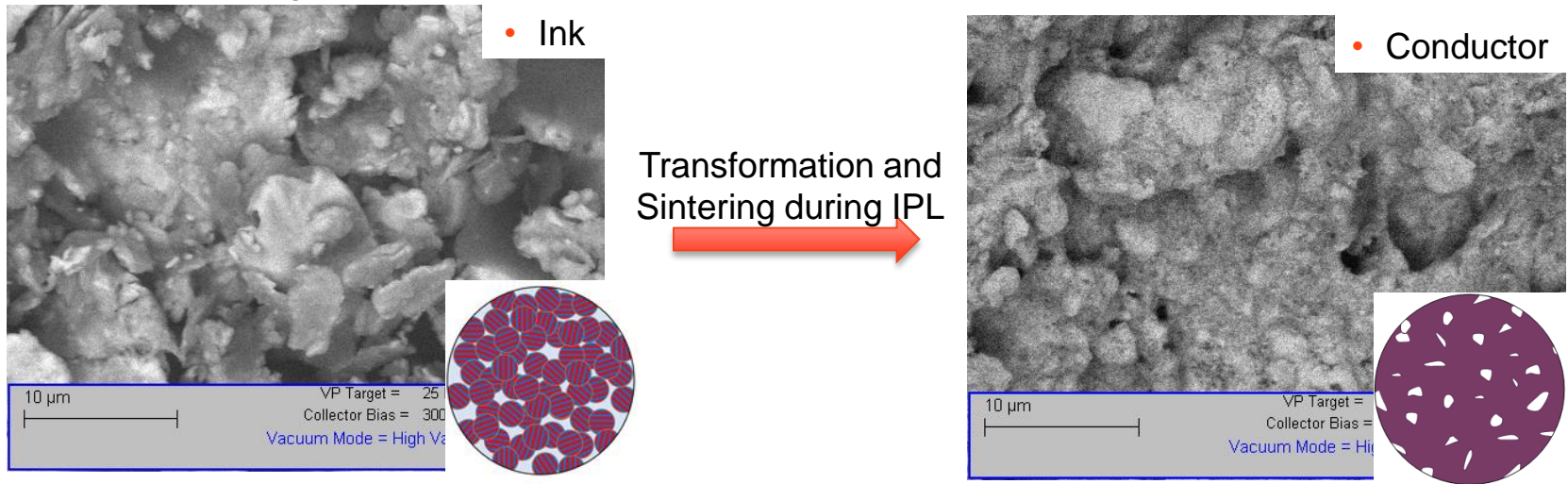
- Cellulose interferes with transformation to high temperature/low conductivity phase & increases resistance.



Cross-sectional areas ~ 1 mm<sup>2</sup>;  
1:1 aspect ratios, in a single print  
pass & single IPL event

# Summary

- Transformational material
  - An ink containing: Composite particles
  - Transformation during IPL sinter:
  - A conductor: Sintered conductive line of high temperature phase
- For printed electronics
  - Printable at high aspect ratios.
  - Sinterable to low Resistance per length ( $<10 \text{ m}\Omega/\text{mm}$ ).
  - Sintering ok for low temperature substrates

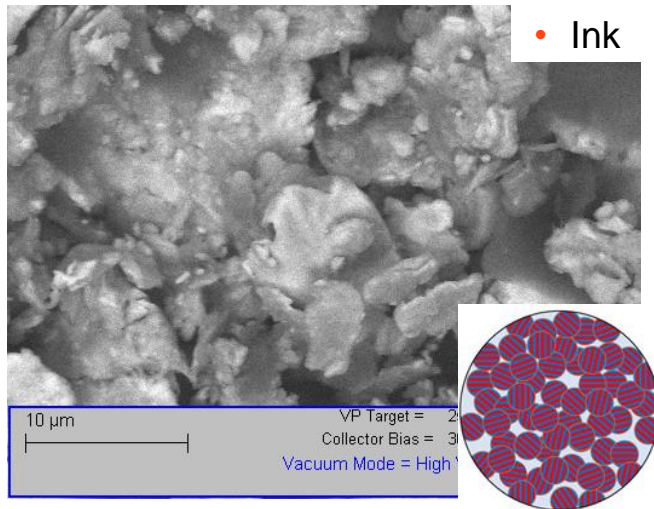


# Contact

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Transformation and  
Sintering during IPL

